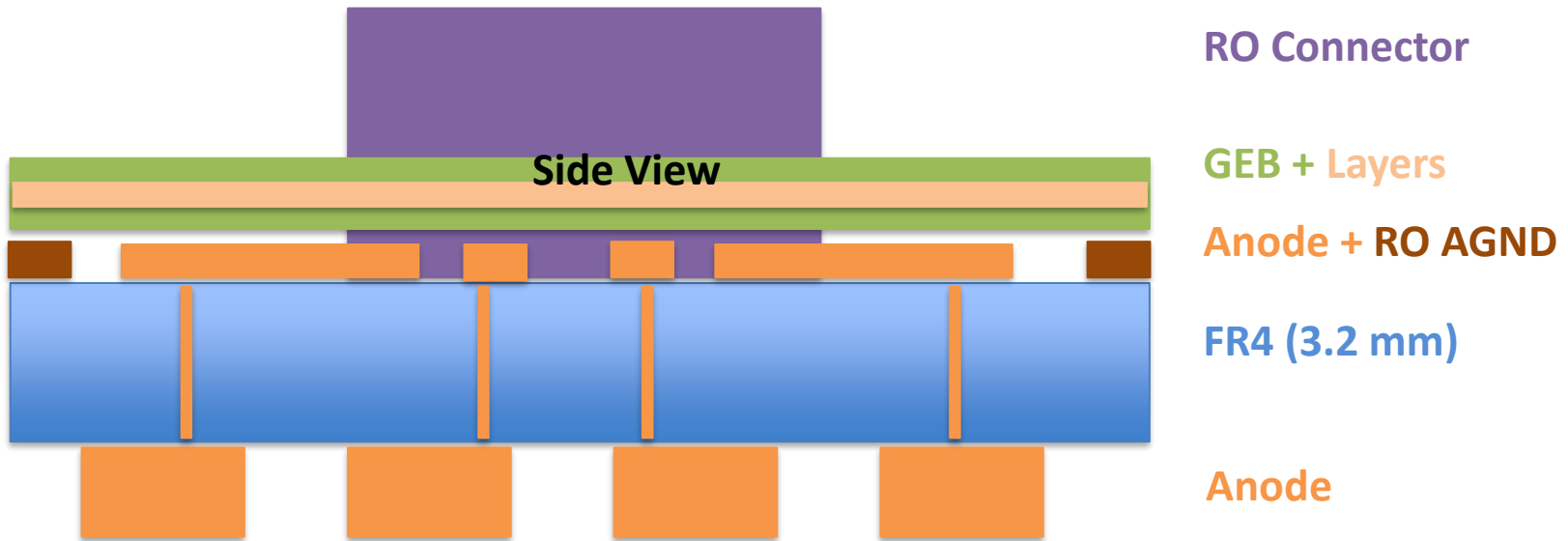
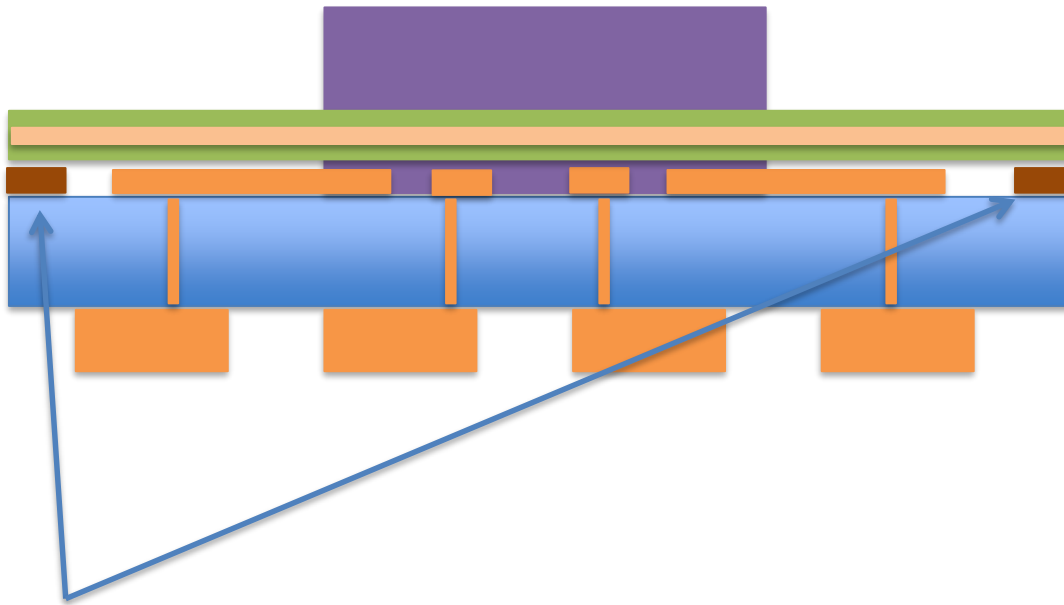


RO board GE1/1 layout



Side View



RO Connector

GEB + Layers

Anode + RO AGND

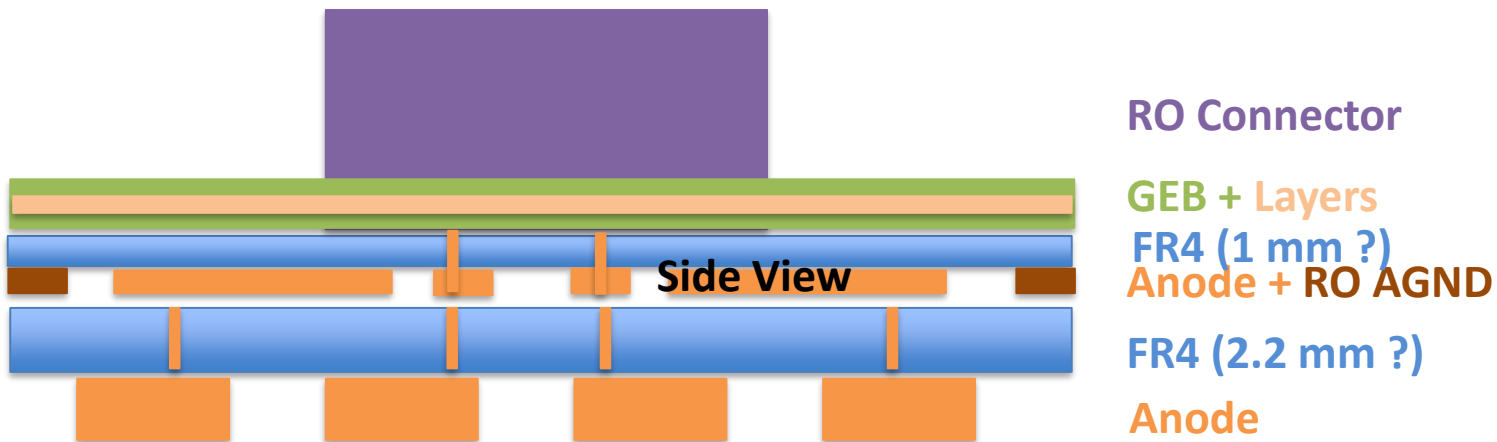
FR4 (3.2 mm)

Anode

No copper layer on the top surface of the RO board

Cost ~ 1 kCHF

Production time 1,5 months



Two layer PCB

3.2 mm total thick PCB

~ 1 mm shielding layer on top of regular RO board ~ 2.2 mm thick

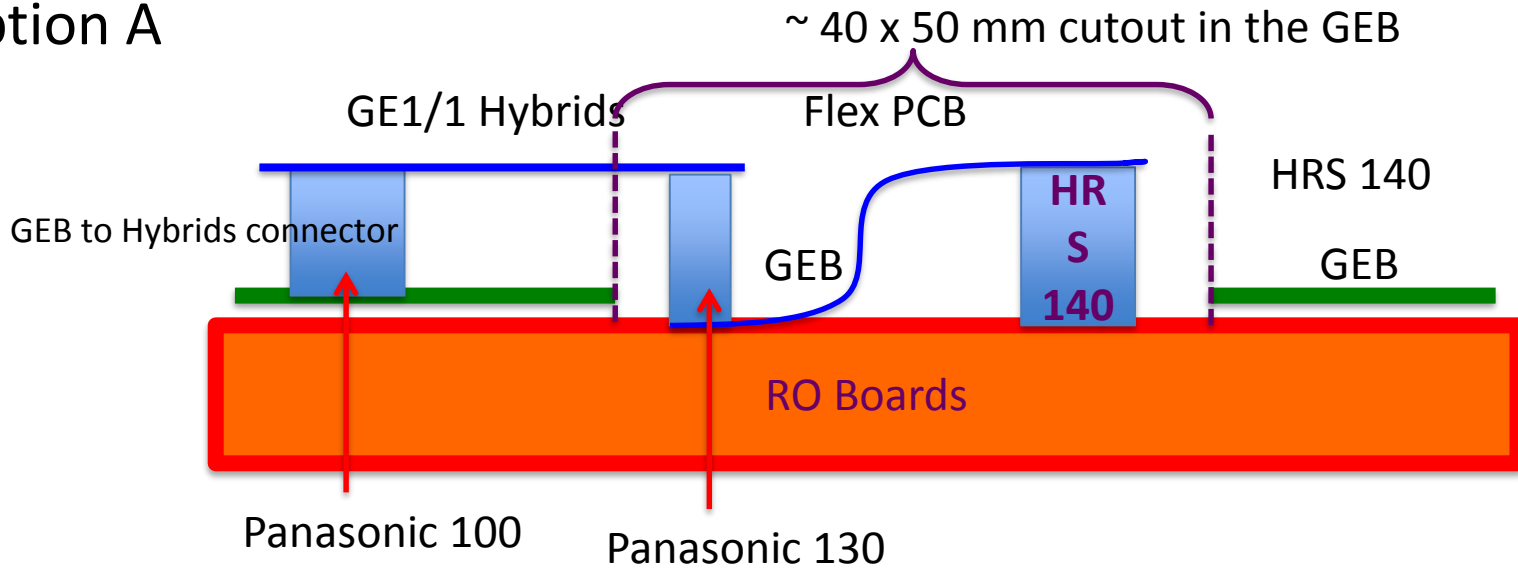
Do we need to keep or not the copper layer RO AGND?

Time 3 months

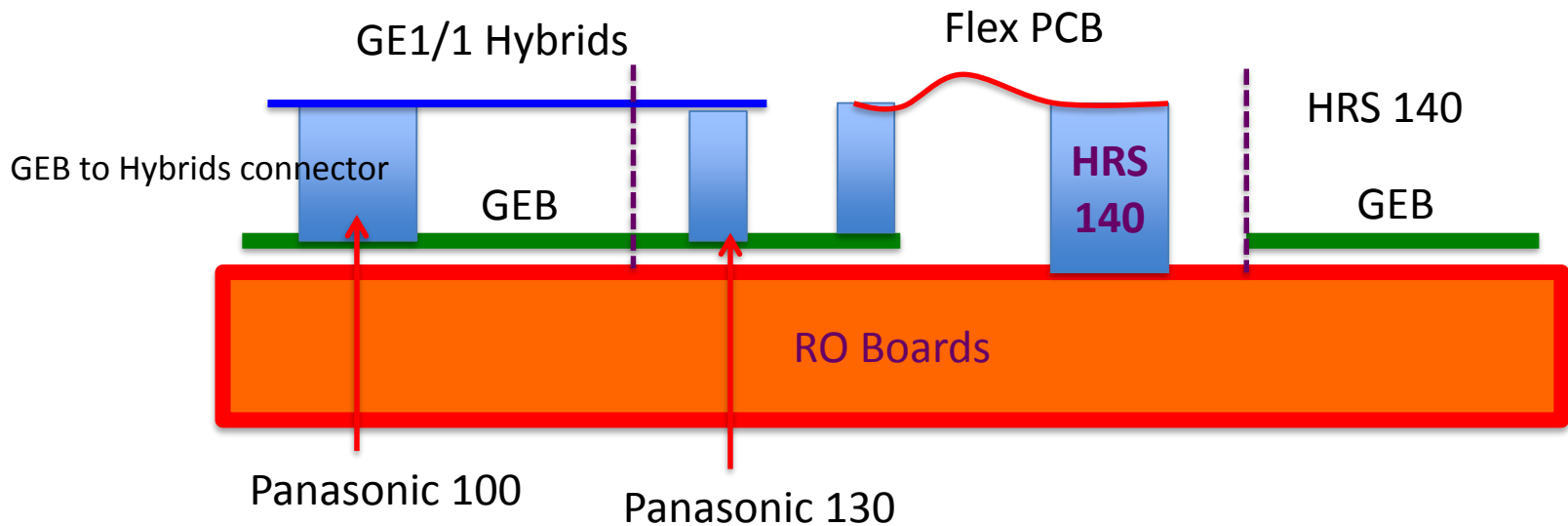
Cost 2 kCHF

Strip capacitance test, GE2/1 strip shape on the GE1/1 RO board,
How many config, in terms of thickness, shi

Option A



Option B



Option C

